IN THE CLAIMS

Please amend the claims as follows:

- 1. (original) A printed circuit board comprising a substrate, a plurality of electronic components, and a pattern of metal tracks (1) on said substrate for connecting said electronic components, said metal tracks (1) being covered with a protective non-conductive layer, wherein said board further comprises a fuse, said fuse comprising a narrowed metal track (3) within the pattern, characterized in that said narrowed metal track (3) is uncovered such that it is exposed to air.
- (original) The printed circuit board according to claim 1,
 wherein further an area (4) of at least 0.5 mm, preferably at least
 1 mm extending from said narrowed metal track (1) is uncovered.
- 3. (currently amended) The printed circuit board according to claim 1—or—2, wherein further a distance of at least 1.5 mm, preferably at least 2 mm of the ends (6) of the wider metal tracks (1) extending from both ends of the narrowed metal track (3) are uncovered.

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- 4. (currently amended) The printed circuit board according to claim 1, 2 or 3, wherein the width of said narrowed metal track (3) is less than 0.3 mm, preferably less than 0.2 mm.
- 5. (currently amended) The printed circuit board according to any of the previous claims 1 4claim 1, wherein a slot (5) is provided in the substrate alongside substantially the entire length of the narrowed metal track (3) at both sides thereof.
- 6. (original) The printed circuit board according to claim 5, wherein said slots (5) are located at a distance of less than 2 mm, preferably less than 1.5 mm from the narrowed metal track (3).
- 7. (currently amended) The printed circuit board according to claim 5—or 6, wherein the area (4) between the narrowed metal track (3) and the slots (5) is substantially uncovered.
- 8. (currently amended) The printed circuit board according to claim 5, 6 or 7, wherein the width of the slots (5) is at least 0.5 mm, preferably at least 1 mm.

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- 9. (currently amended) An electronic ballast for a gas discharge lamp comprising a printed circuit board according to any of the preceding claims 1 8claim 1.
- 10. (original) A method for producing a printed circuit board comprising a substrate, a plurality of electronic components, and a pattern of metal tracks (1) on said substrate for connecting said electronic components, said metal tracks (1) being covered with a protective non-conductive layer, wherein said board is further provided with a fuse by providing a narrowed metal track (3) within the pattern, characterized in that said narrowed metal track (3) is not covered with a protective non-conductive layer such that it remains exposed to air.

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